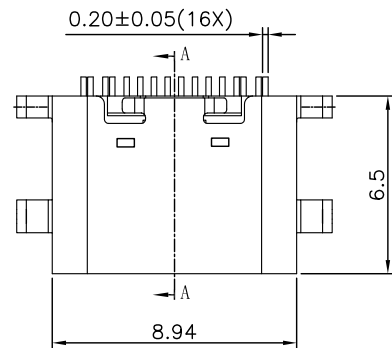
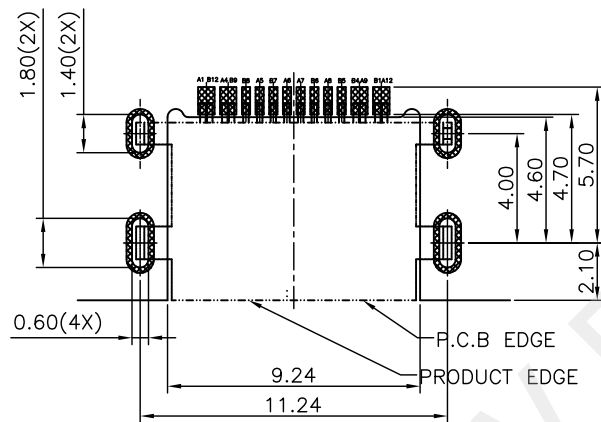
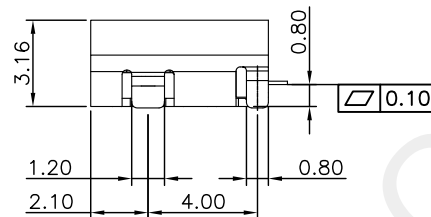
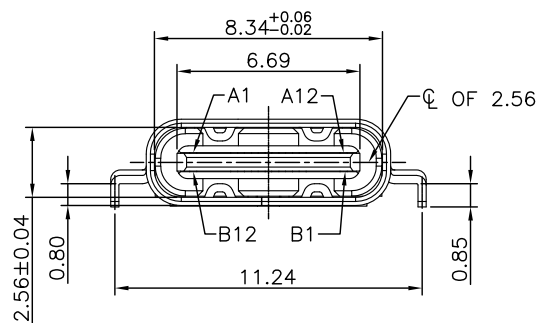
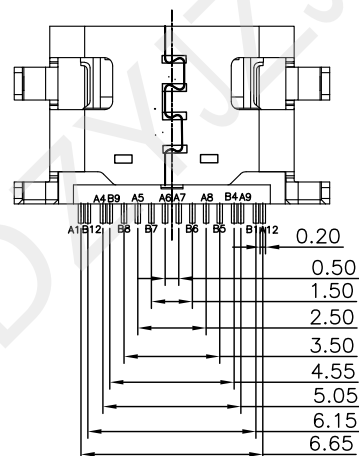


SECTION: A-A



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 0.80MM;DEFAULT TOLERANCE:±0.05



NOTE:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.

2.TERMINAL: COPPER ALLOY(C2680)

3.FRONT SHELL: STAINLESS STEEL(SUS304)

2.PLATING SPECIFICATION:

2-1.TERMINAL:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

PLATING SPECIFICATIONS FOLLOW THE P/N

2-3.MID PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~1.2kgf.

3-2.REMOVAL FORCE: 0.6kgf~1.5kgf.

3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. VOLTAGE RATING:5 V DC/AC (RMS. max)

CURRENT RATING:5 AMPS. FOR TOTAL VBUS/GND PINS;

1.25AMPS FOR CC PIN,0.25 AMPS. FOR ALL OTHER CONTACT.

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL

BE MAINTAINED FOR 10 SECONDS AT 260°C.



深圳市华宇创精密电子有限公司

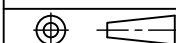
TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X' ±2" X.X' ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB TYPE C 母座16P 单排SMT沉板0.8 L=6.5

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC694-USBC16-080

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2507221718

SHEET NO.

1 OF 1